



**IPC-7711C/7721C-AM1**

# **Rework, Modification and Repair of Electronic Assemblies**

## **Amendment 1**

Developed by the Repairability Subcommittee (7-34) of the Product Assurance Committee (7-30) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

Contact:

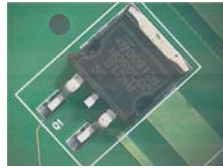
IPC

# Table of Contents

## PART 2 Rework

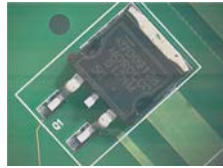
### 3.1.2 D-Pak Removal



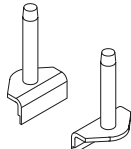
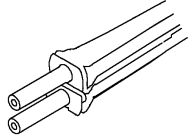
Procedure	Description	Board Type	Skill Level	Level of Conformance
3.1.2	Flux Application Method – Tweezers Method	R,F,W,C	Advanced	High



### 5.9 D-Pak Installation

Procedure	Description	Board Type	Skill Level	Level of Conformance
5.9	Flux Application Method – Point-to-Point Method	R,F,W,C	Advanced	High



	Revision: <b>C Amendment 1</b> Date: <b>7/20</b> <b>D-Pak Removal</b> <b>Tweezers Method</b>	Number: <b>3.1.2</b>	
		Board Type: R,F,W,C See 1.4.2 Skill Level: Advanced See 1.4.3 Level of Conformance: High See 1.5.1	

### GENERAL REQUIREMENTS

Clauses 1.7 (Basic Considerations), 1.8 (Workstations, Tools, Materials and Processes) and 1.9 (Lead Free) provide important information and guidance about the use of this procedure, including but not limited to tin-lead and lead-free alloys. This procedure is also applicable to lead free products.

### EQUIPMENT REQUIRED

Soldering system  
Tweezers handpiece  
Removal tips

### MATERIALS

Flux-Core Solder  
Flux  
Cleaner

### PROCEDURE

1. Remove conformal coating (if any) and clean the area of any contamination, oxides or residues.
2. Install removal tips into tweezers handpiece.
3. Start with tip temperature of approximately 315 °C [599 °F] and change as necessary.
4. Apply flux to the thermal plane land and leads. (See Figure 1.)
5. Clean the tip. Procedure 2.8
6. Tin the bottom and inside edges of tweezers tips with solder. (See Figure 2.)
7. Lower tips over component and squeeze handpiece contacting the termination and leads. (See Figure 3.)
8. Confirm solder melt of all joints and lift component from PCB. (See Figure 4.)
9. Release component from tips by wiping on a heat resistant surface.
10. Re-tin tips with solder and return handpiece to its stand.
11. Prepare land for component replacement. (See Figure 5.)
12. Clean, if required, and inspect.

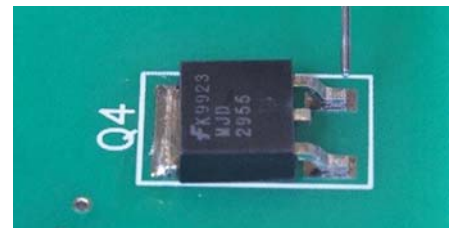


Figure 1 Apply Flux.

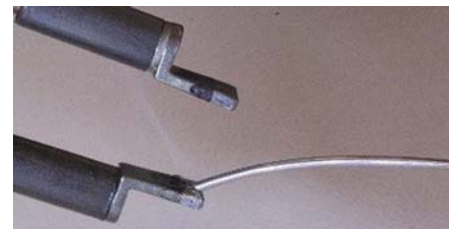


Figure 2 Tin Tips with Solder.

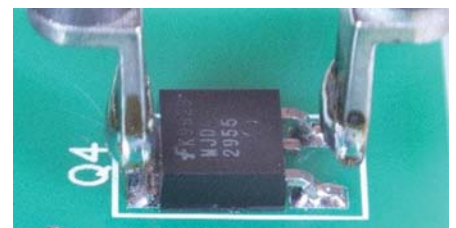


Figure 3 Lower Tips Over Component and Squeeze Handpiece.



Figure 4 Confirm Solder Melt and Lift Component.

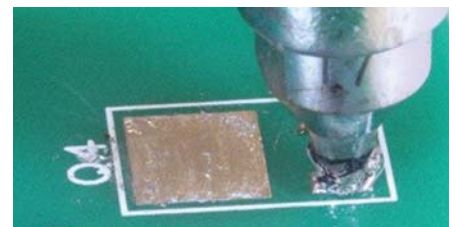


Figure 5 Prepare Lands for Component Replacement. Component.